

View Online at <https://aerobasegroup.com/nsn/5910-01-482-0964>

**Body Style:**

Chip type

**Reliability Indicator:**

Established

**Reliability Failure Rate Level In Percent:**

0.0100

**Terminal Length:**

0.5 millimeters

**Body Length:**

2.0 millimeters

**Body Width:**

1.2 millimeters

**Body Height:**

1.3 millimeters

**Schematic Diagram Designator:**

No common or grounded electrode (s)

**End Application:**

Circuit card assembly

**Capacitance Value Per Section:**

220.000 picofarads single section

**Nonderated Operating Temp:**

Between -55.0 degrees celsius and 125.0 degrees celsius

**Temperature Coefficient Of Capacitance Per Section In Ppm Per Deg Celsius:**

0.0 single section

**Nonderated Continuous Voltage Rating And Type Per Section:**

100.0 dc single section

**Tolerance Of Temperature Coefficient Per Section In Ppm Per Deg Celsius:**

-15.0/+15.0 single section

**Criticality Code Justification:**

Agav

**Tolerance Range Per Section:**

-1.00/+1.00 percent single section

**Case Material:**

Ceramic or glass

**Dissipation Factor At Reference Temperature In Percent:**

0.0500

**Special Features:**

Termination finish is base metallization-barrier metal-solder coated min thick is 60 micro-inches (tin/lead alloy)

**Test Data Document:**

81349-mil-c-55681 specification (includes engineering type bulletins, brochures, etc., that reflect specification type data in specification format; excludes commercial catalogs, industry directories, and similar trade publications, reflecting general type data on certain environmental and performance requirements and test conditions that are shown as "typical", "average", "", etc.).

**Terminal Type And Quantity:**

2 bonding pad

**Shelf Life:**

N/a

**Unit Of Measure:**

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**Demilitarization:**

Yes - demil/mli

**Fiig:**

A010b0